

PDFN5X6-8L P Channel Enhancement 沟道增强型 MOS Field Effect Transistor 场效应管

■ Features 特点

Low on-resistance 低导通电阻

$R_{DS(ON)}=8.5\text{m}\Omega$ (Type)@ $V_{GS}=-10\text{V}$

$R_{DS(ON)}=10\text{m}\Omega$ (Type)@ $V_{GS}=-4.5\text{V}$

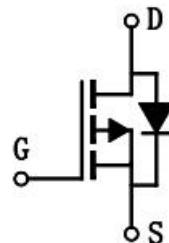
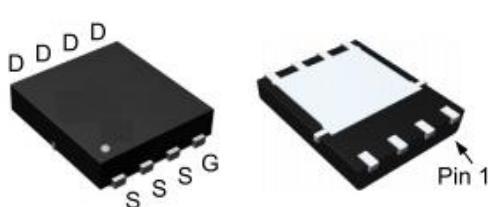
■ Applications 应用

Load Switch 负载开关

PWM Application 脉宽调制

Power Management 电源管理

■ Internal Schematic Diagram 内部结构



■ Absolute Maximum Ratings 最大额定值

Characteristic 特性参数	Symbol 符号	Rating 额定值	Unit 单位
Drain-Source Voltage 漏极-源极电压	BV_{DSS}	-40	V
Gate- Source Voltage 栅极-源极电压	V_{GS}	± 20	V
Drain Current (continuous)漏极电流-连续	I_D (at $T_C = 25^\circ\text{C}$ at $T_A = 25^\circ\text{C}$)	-70 -20	A
Drain Current (pulsed)漏极电流-脉冲	I_{DM}	-140	A
Total Device Dissipation 总耗散功率	P_{TOT} (at $T_C/T_A = 25^\circ\text{C}$)	59.5/2.08	W
Avalanche Energy(Single Pulse)雪崩能量	E_{AS}	125	mJ
Thermal Resistance Junction-Ambient 热阻	$R_{\theta JA}$	60	°C/W
Junction/Storage Temperature 结温/储存温度	T_J, T_{stg}	-55~150	°C



安徽富信半导体科技有限公司

ANHUI FOSAN SEMICONDUCTOR TECHNOLOGY CO., LTD.

FSN70P04

■ Electrical Characteristics 电特性

($T_A=25^\circ\text{C}$ unless otherwise noted 如无特殊说明, 温度为 25°C)

Characteristic 特性参数	Symbol 符号	Min 最小值	Typ 典型值	Max 最大值	Unit 单位
Drain-Source Breakdown Voltage 漏极-源极击穿电压($I_D = -250\mu\text{A}, V_{GS} = 0\text{V}$)	BV_{DSS}	-40	—	—	V
Gate Threshold Voltage 栅极开启电压($I_D = -250\mu\text{A}, V_{GS} = V_{DS}$)	$V_{GS(\text{th})}$	-1.0	-1.5	-2.5	V
Zero Gate Voltage Drain Current 零栅压漏极电流($V_{GS} = 0\text{V}, V_{DS} = -40\text{V}$)	I_{DSS}	—	—	-1	μA
Gate Body Leakage 栅极漏电流($V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$)	I_{GSS}	—	—	± 100	nA
Static Drain-Source On-State Resistance 静态漏源导通电阻($I_D = -20\text{A}, V_{GS} = -10\text{V}$) ($I_D = -10\text{A}, V_{GS} = -4.5\text{V}$)	$R_{DS(\text{ON})}$	—	8.5 10	13 18	$\text{m}\Omega$
Diode Forward Voltage Drop 内附二极管正向压降($I_{SD} = -1\text{A}, V_{GS} = 0\text{V}$)	V_{SD}	—	-0.7	-1	V
Input Capacitance 输入电容 ($V_{GS} = 0\text{V}, V_{DS} = -20\text{V}, f = 1\text{MHz}$)	C_{ISS}	—	3125	—	pF
Common Source Output Capacitance 共源输出电容($V_{GS} = 0\text{V}, V_{DS} = -20\text{V}, f = 1\text{MHz}$)	C_{OSS}	—	812	—	pF
Reverse Transfer Capacitance 反馈电容 ($V_{GS} = 0\text{V}, V_{DS} = -20\text{V}, f = 1\text{MHz}$)	C_{RSS}	—	575	—	pF
Total Gate Charge 棚极电荷密度 ($V_{DS} = -20\text{V}, I_D = -20\text{A}, V_{GS} = -10\text{V}$)	Q_g	—	80	—	nC
Gate Source Charge 棚源电荷密度 ($V_{DS} = -20\text{V}, I_D = -20\text{A}, V_{GS} = -10\text{V}$)	Q_{gs}	—	14	—	nC
Gate Drain Charge 棚漏电荷密度 ($V_{DS} = -20\text{V}, I_D = -20\text{A}, V_{GS} = -10\text{V}$)	Q_{gd}	—	19	—	nC
Turn-ON Delay Time 开启延迟时间 ($V_{DS} = -20\text{V}, I_D = -1\text{A}, R_{\text{GEN}} = 6\Omega, V_{GS} = -10\text{V}$)	$t_{d(\text{on})}$	—	19	—	ns
Turn-ON Rise Time 开启上升时间 ($V_{DS} = -20\text{V}, I_D = -1\text{A}, R_{\text{GEN}} = 6\Omega, V_{GS} = -10\text{V}$)	t_r	—	16	—	ns
Turn-OFF Delay Time 关断延迟时间 ($V_{DS} = -20\text{V}, I_D = -1\text{A}, R_{\text{GEN}} = 6\Omega, V_{GS} = -10\text{V}$)	$t_{d(\text{off})}$	—	115	—	ns
Turn-OFF Fall Time 关断下降时间 ($V_{DS} = -20\text{V}, I_D = -1\text{A}, R_{\text{GEN}} = 6\Omega, V_{GS} = -10\text{V}$)	t_f	—	71	—	ns

■ Typical Characteristic Curve 典型特性曲线

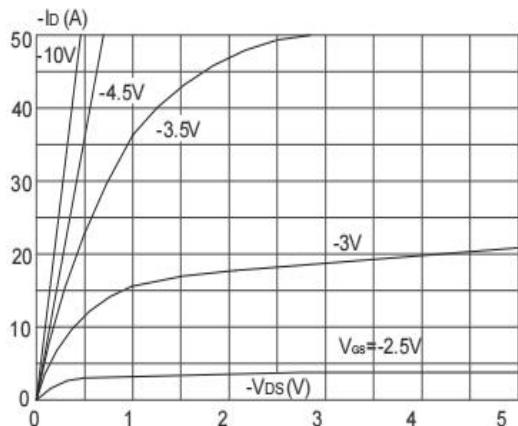


Figure 1: Output Characteristics

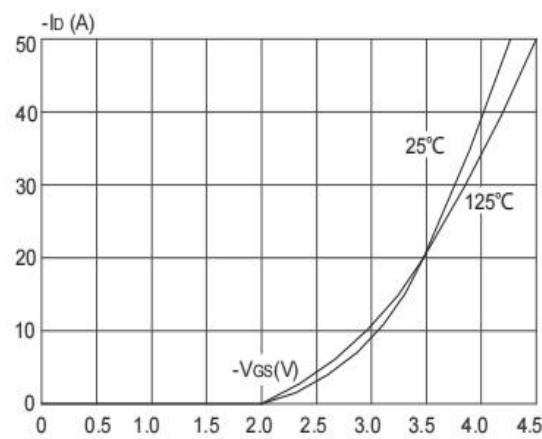


Figure 2: Transfer Characteristics

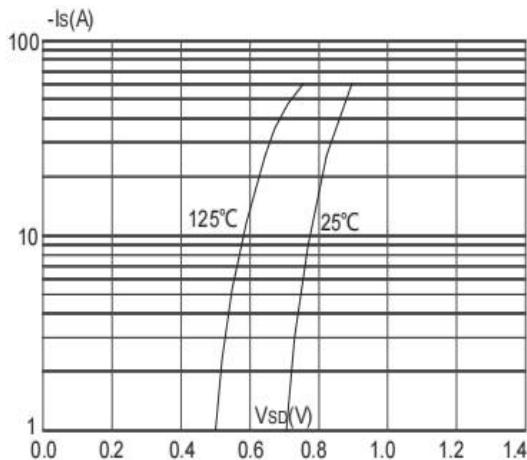


Figure 3: Diode Characteristics

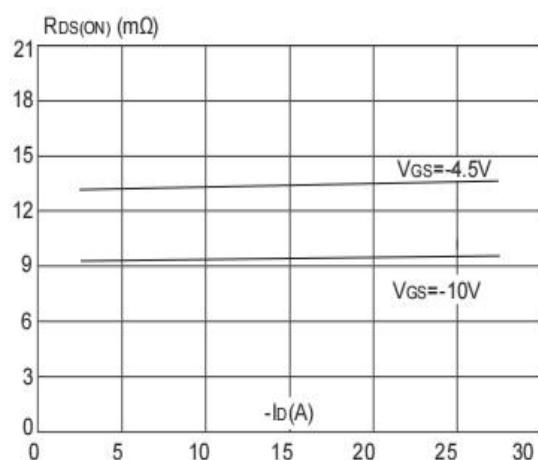


Figure 4: On-Resistance vs. Drain Current

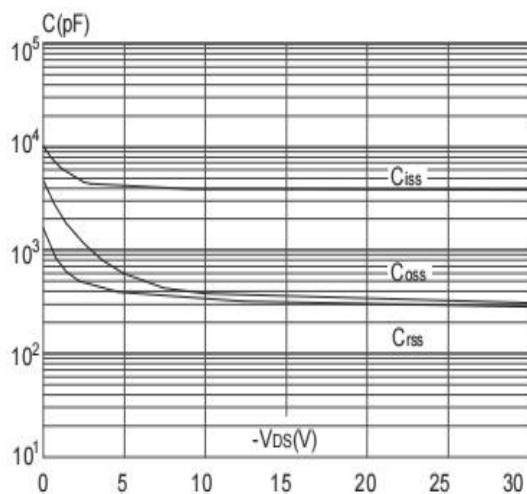


Figure 5: Capacitance Characteristics

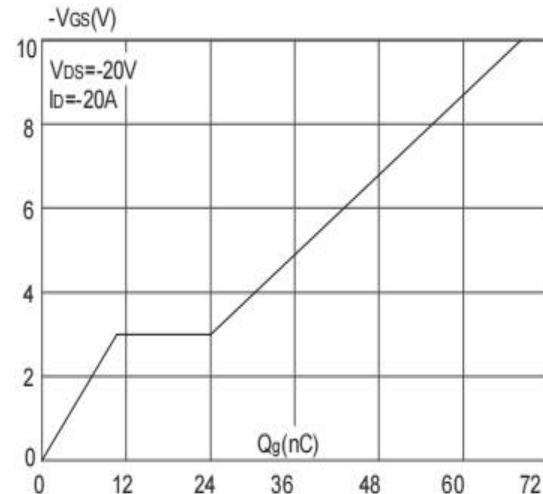


Figure 6: Gate-Charge Characteristics

■ Typical Characteristic Curve 典型特性曲线

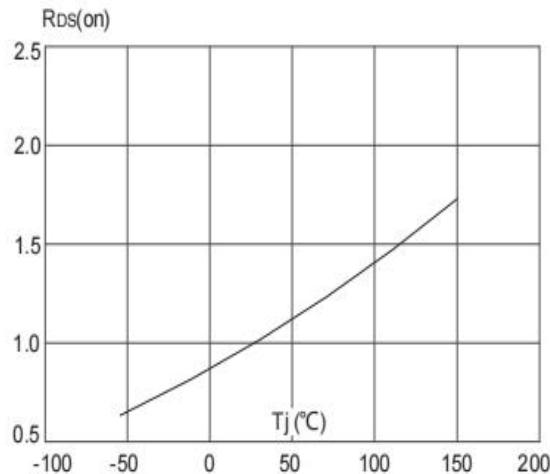


Figure 7: On-Resistance vs. T_j

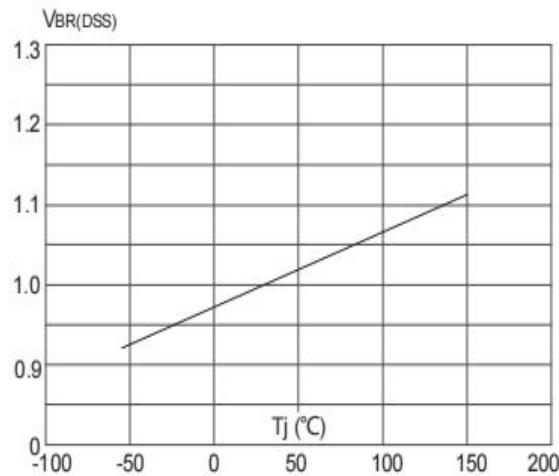


Figure 8: Breakdown Voltage vs. T_j

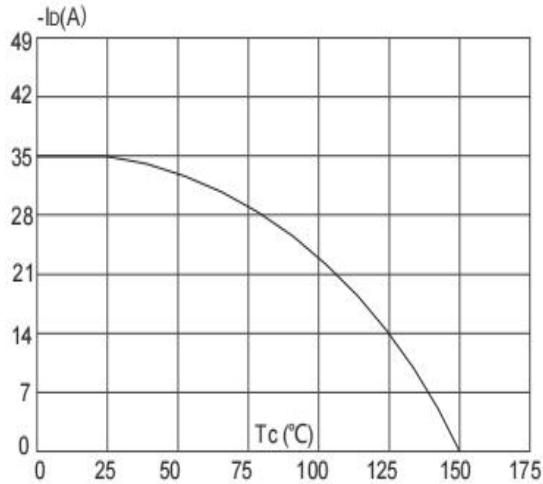


Figure 9: Drain Current Characteristics

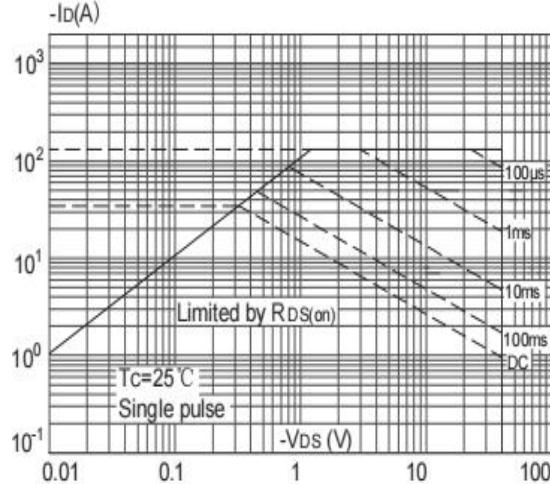


Figure 10: Safe Operating Area

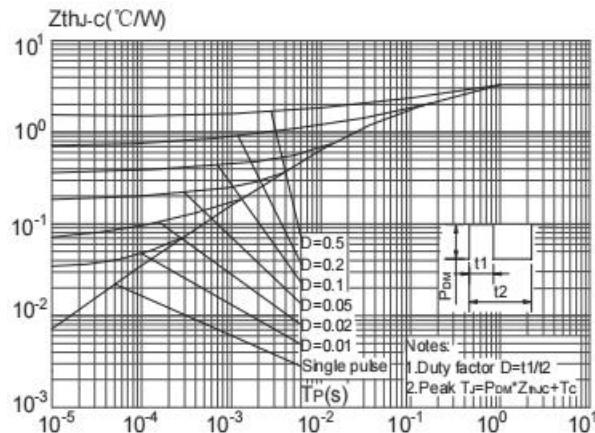


Figure 11: Transient Thermal Response Curve

■ Dimension 外形封装尺寸

